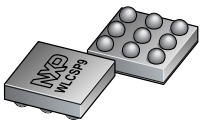

SOT1385-2

WLCSP9, wafer level chip-scale package; 9 bumps; 0.5 mm pitch, 1.49 mm x 1.49 mm x 0.555 mm body (backside coating included)

29 March 2018 **Package information**

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP9
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	6-3-2018
Manufacturer package code	98ASA01215D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	1.49	-	mm
E	package width		-	-	1.49	-	mm
A	seated height		-	-	0.555	-	mm
e	nominal pitch		-	-	0.5	-	mm
n_2	actual quantity of termination		-	-	9	-	A/A

WLCSP9, wafer level chip-scale package; 9 bumps; 0.5 mm pitch, 1.49 mm x 1.49 mm x 0.555 mm body (backside coating included)

2. Package outline

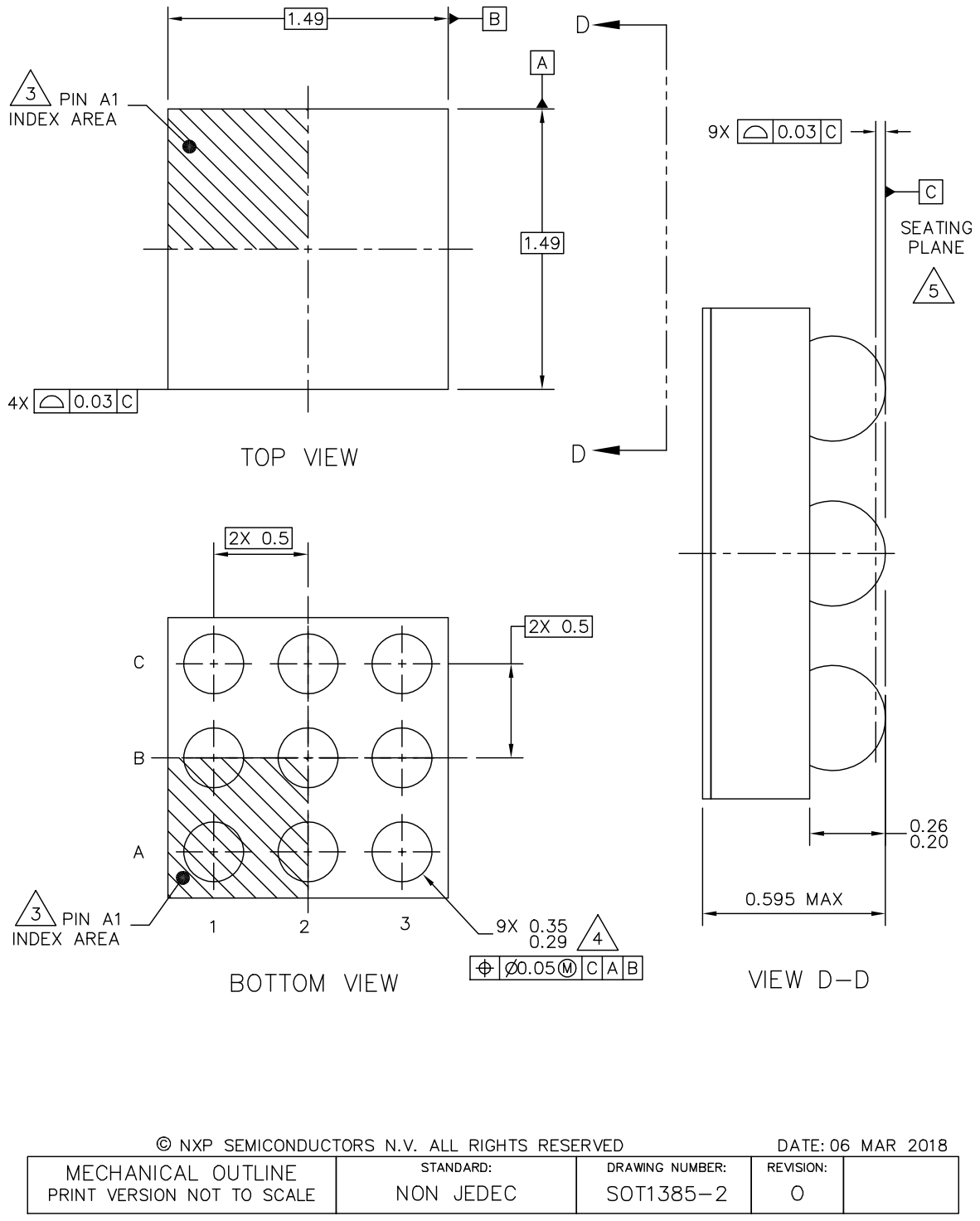

Fig. 1. Package outline SOT1385-2

WLCSP9, wafer level chip-scale package; 9 bumps; 0.5 mm pitch, 1.49 mm x 1.49 mm x 0.555 mm body (backside coating included)

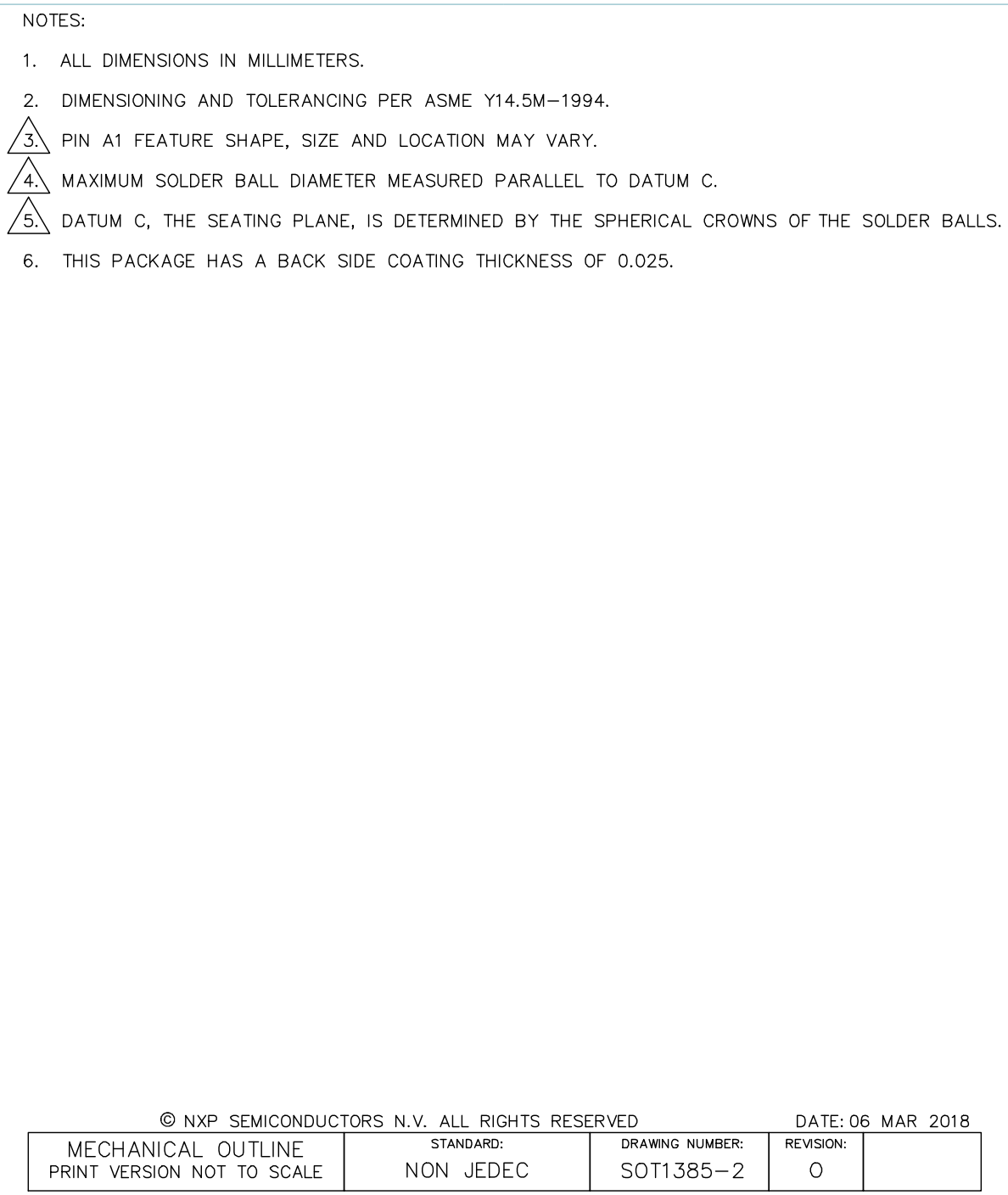

Fig. 2. Package outline note WLCSP9 (SOT1385-2)

3. Soldering

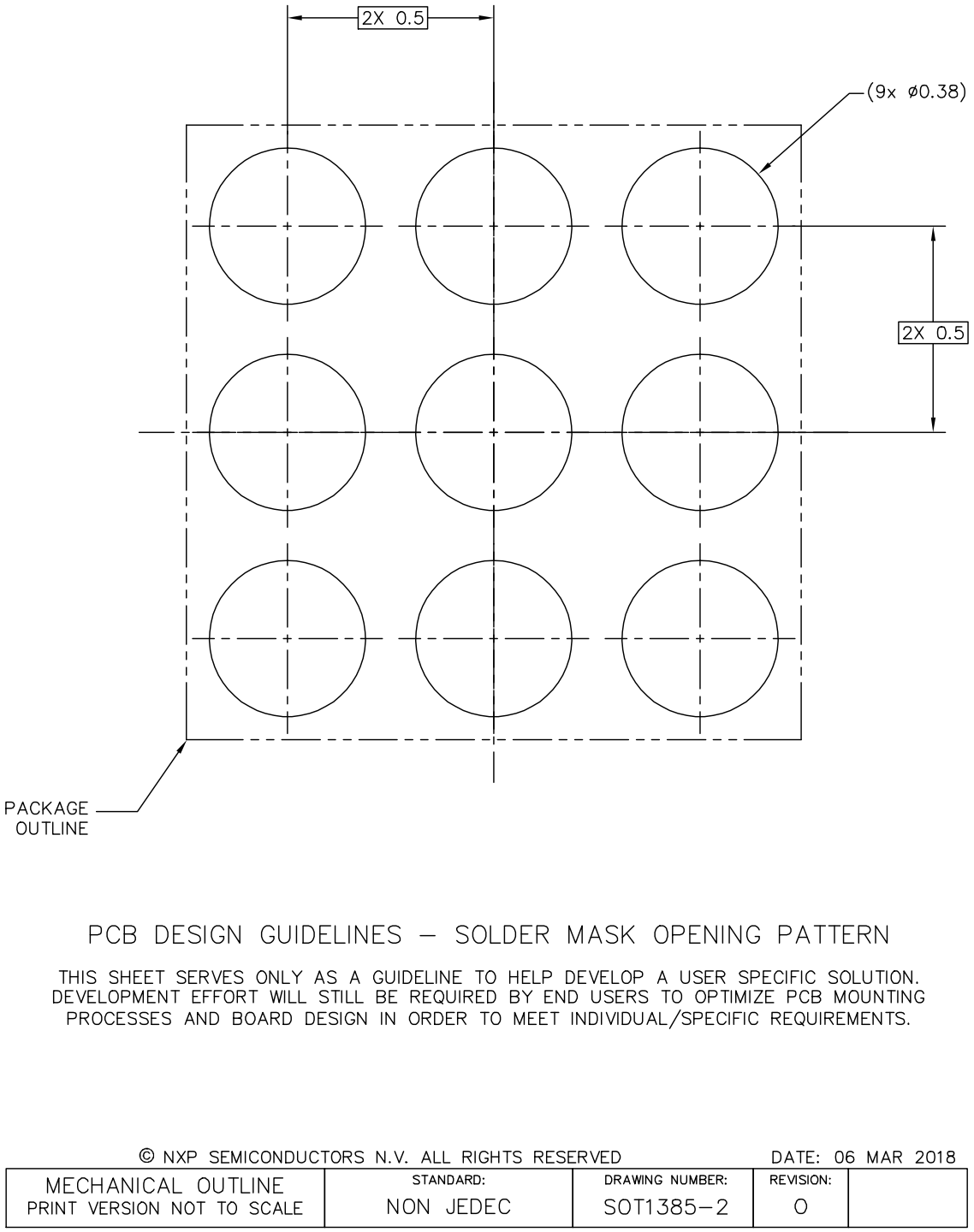

Fig. 3. Reflow soldering footprint for SOT1385-2

WLCSP9, wafer level chip-scale package; 9 bumps; 0.5 mm pitch, 1.49 mm x 1.49 mm x 0.555 mm body (backside coating included)

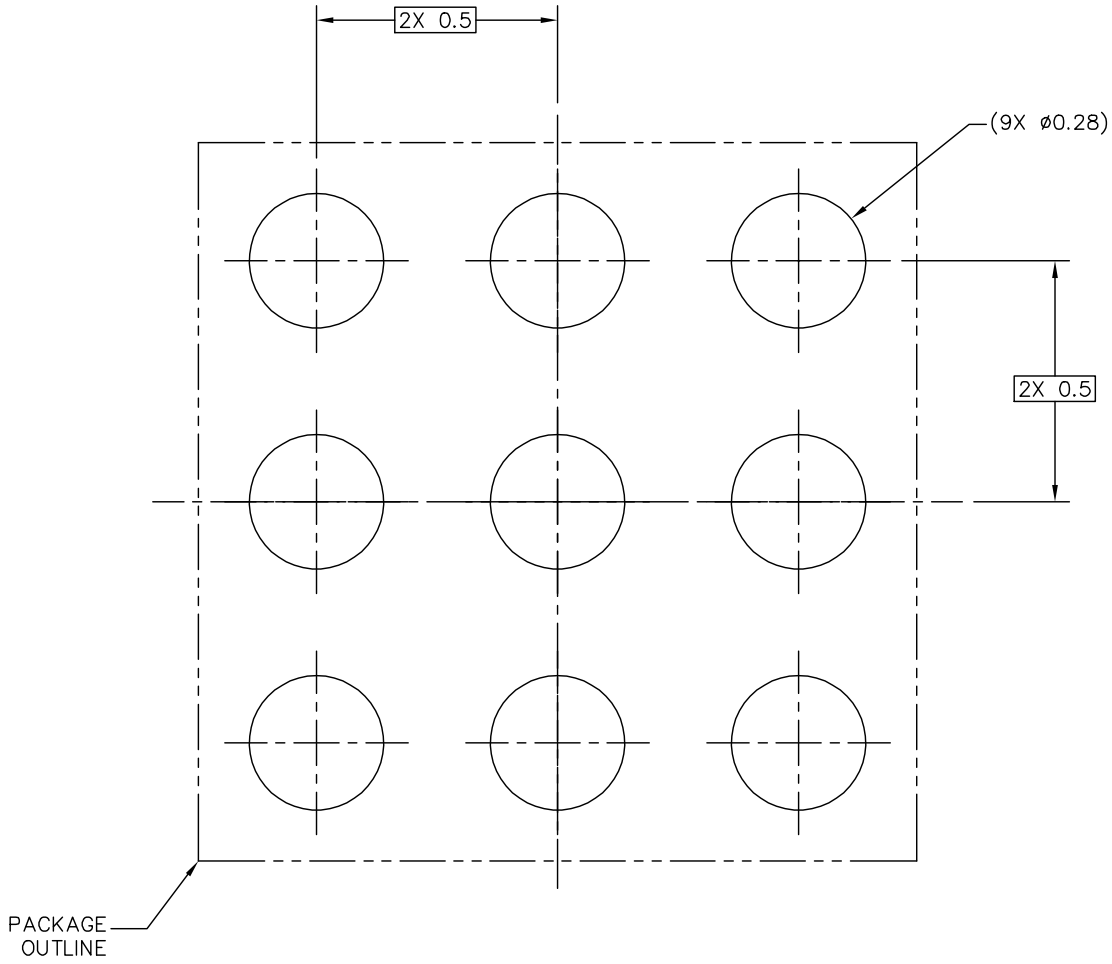

Fig. 4. Reflow soldering footprint part2 for WLCSP9 (SOT1385-2)

WLCSP9, wafer level chip-scale package; 9 bumps; 0.5 mm pitch, 1.49 mm x 1.49 mm x 0.555 mm body (backside coating included)

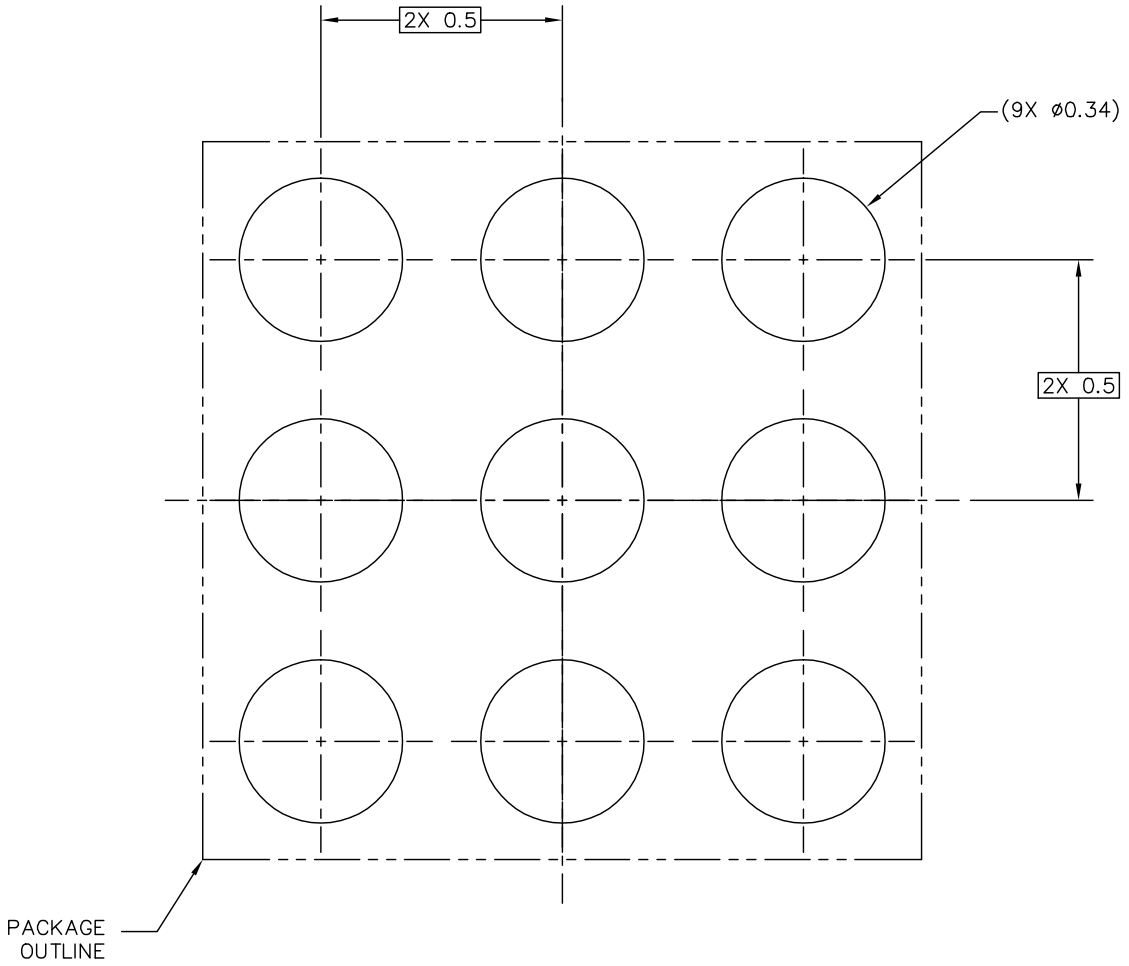

Fig. 5. Reflow soldering footprint part3 for WLCSP9 (SOT1385-2)

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5. Contents

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Date of release: 29 March 2018